ORIENTAL® SEMICONDUCTOR

General Description

SFGMOS® MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially optimized for synchronous rectification systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery

RoHS compliant

Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply
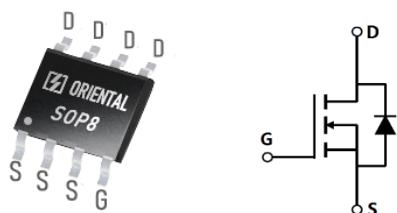
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min}$ @ $T_{j(max)}$	80	V
$I_{D, pulse}$	44	A
$R_{DS(ON), max}$ @ V_{GS}=10V	10	mΩ
Q_g	31.5	nC

Marking Information

Product Name	Package	Marking
SFG08S10BF	SOP8	SFG08S10B

Package & Pin information

Absolute Maximum Ratings at T_j=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	80	V
Gate-source voltage	V_{GS}	±20	V
Continuous drain current[1], T_C=25 °C	I_D	11	A
Pulsed drain current[2], T_C=25 °C	$I_{D, pulse}$	44	A
Continuous diode forward current[1], T_C=25 °C	I_S	11	A
Diode pulsed current[2], T_C=25 °C	$I_{S, pulse}$	44	A
Power dissipation[3], T_C=25 °C	P_D	4	W
Single pulsed avalanche energy[5]	E_{AS}	132.6	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-ambient[4]	$R_{\theta JA}$	31.3	°C/W

Electrical Characteristics at T_j=25°C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	80			V	V_{GS}=0 V, I_D=250 µA
Gate threshold voltage	$V_{GS(th)}$	1.0		2.5	V	V_{DS}=V_{GS}, I_D=250 µA
Drain-source on-state resistance	$R_{DS(ON)}$		8.5	10.0	mΩ	V_{GS}=10 V, I_D=12 A
Drain-source on-state resistance	$R_{DS(ON)}$		10.0	14.0	mΩ	V_{GS}=4.5 V, I_D=9 A
Gate-source leakage current	I_{GSS}			100	nA	V_{GS}=20 V
				-100		V_{GS}=-20 V
Drain-source leakage current	I_{DSS}			1	µA	V_{DS}=80 V, V_{GS}=0 V

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		2057.0		pF	V_{GS}=0 V, V_{DS}=50 V, f=100 kHz
Output capacitance	C_{oss}		480.1		pF	
Reverse transfer capacitance	C_{rss}		11.9		pF	
Turn-on delay time	$t_{d(on)}$		20.7		ns	V_{GS}=10 V, V_{DS}=50 V, R_G=2 Ω, I_D=10 A
Rise time	t_r		4.8		ns	
Turn-off delay time	$t_{d(off)}$		48.3		ns	
Fall time	t_f		10.7		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		31.5		nC	V_{GS}=10 V, V_{DS}=50 V, I_D=10 A
Gate-source charge	Q_{gs}		5.3		nC	
Gate-drain charge	Q_{gd}		8.8		nC	
Gate plateau voltage	$V_{plateau}$		3.5		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	I_S=12 A, V_{GS}=0 V
Reverse recovery time	t_{rr}		92.7		ns	I_S=10 A, di/dt=100 A/µs
Reverse recovery charge	Q_{rr}		112.1		nC	
Peak reverse recovery current	I_{rrm}		3.5		A	

Note

1) Calculated continuous current based on maximum allowable junction temperature.
2) Repetitive rating; pulse width limited by max. junction temperature.
3) Pd is based on max. junction temperature, using junction-case thermal resistance.
4) The value of $R_{θJA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
5) V_{DD}=50 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams
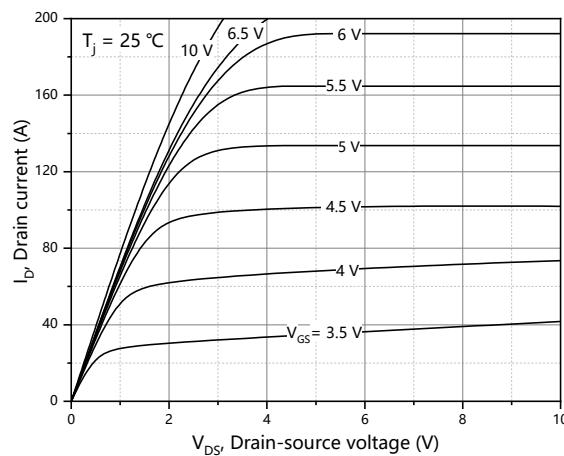
Figure 1. Typ. output characteristics
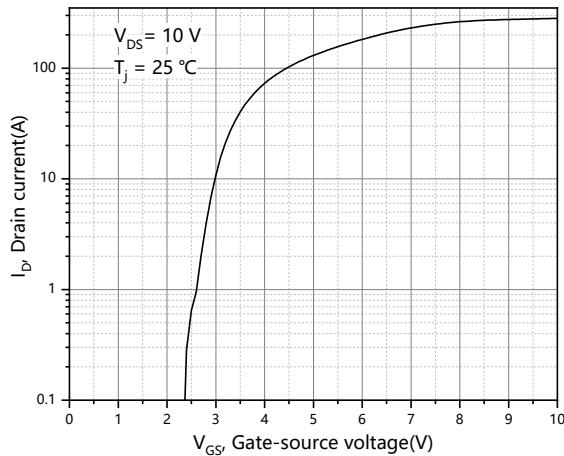
Figure 2. Typ. transfer characteristics
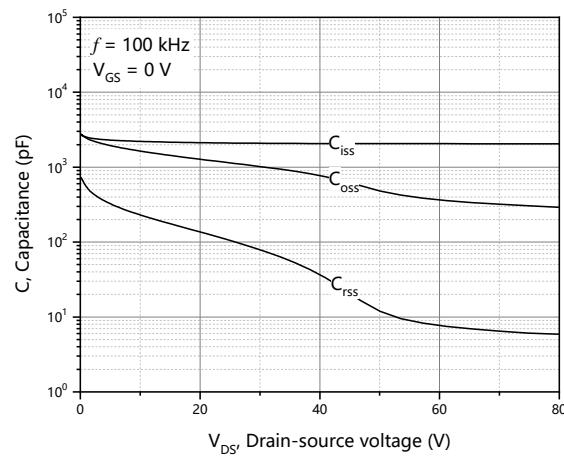
Figure 3. Typ. capacitances
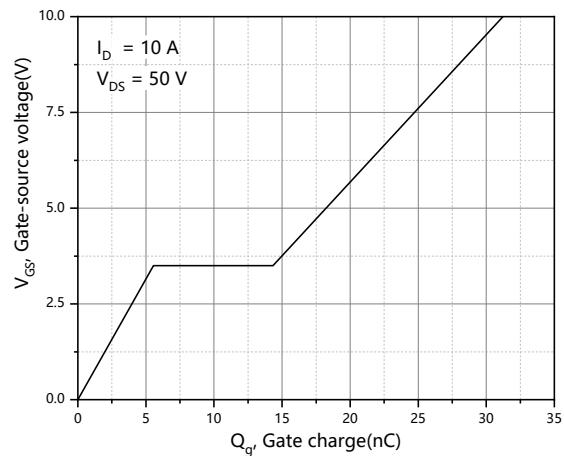
Figure 4. Typ. gate charge
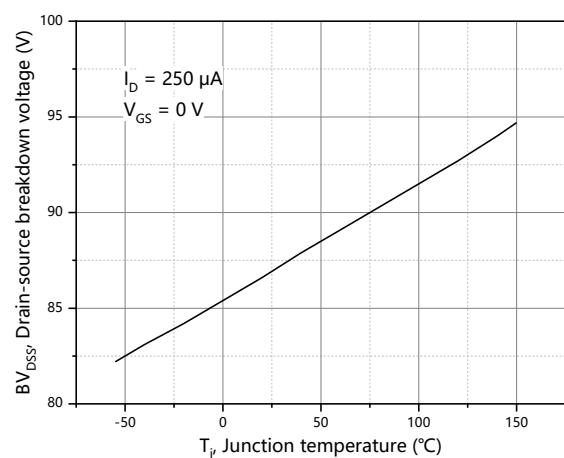
Figure 5. Drain-source breakdown voltage
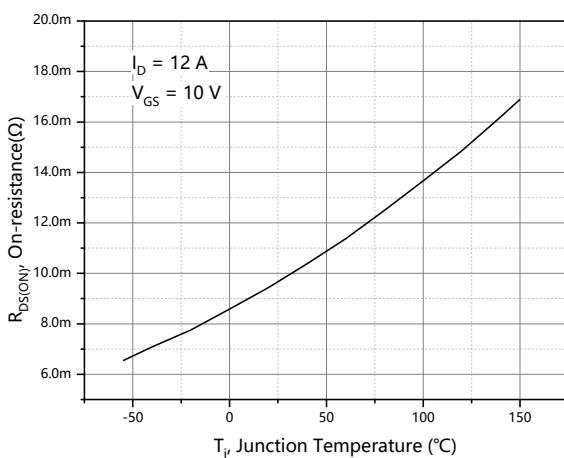
Figure 6. Drain-source on-state resistance
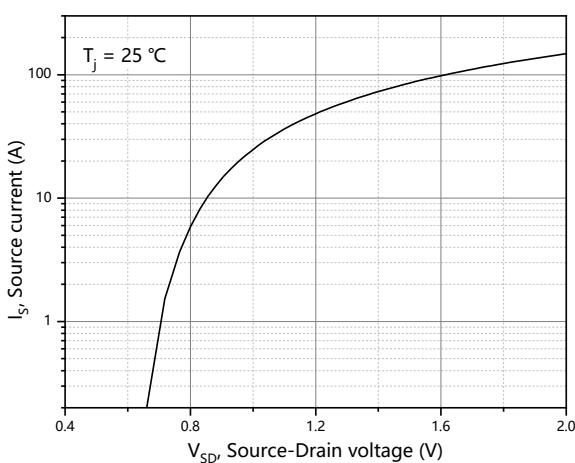
Figure 7. Forward characteristic of body diode
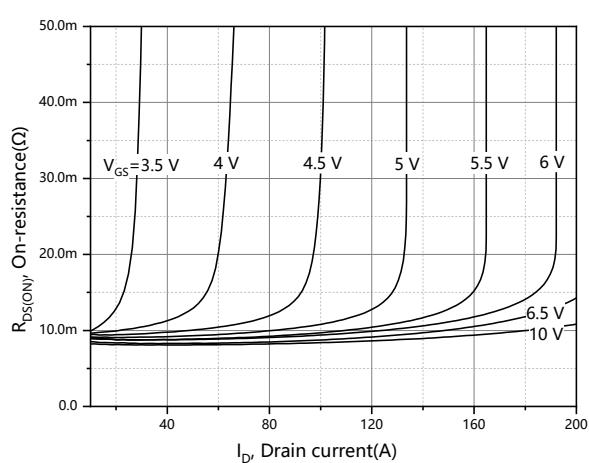
Figure 8. Drain-source on-state resistance
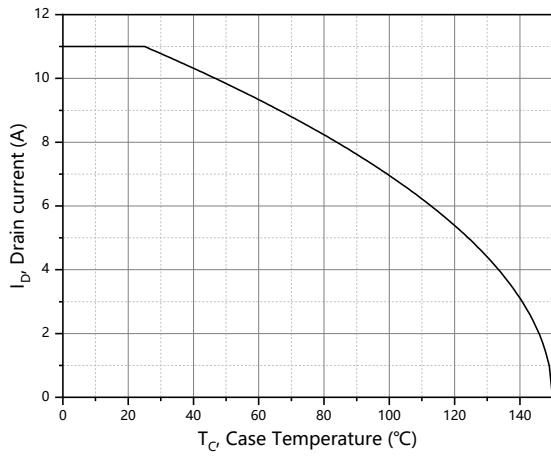
Figure 9. Drain current
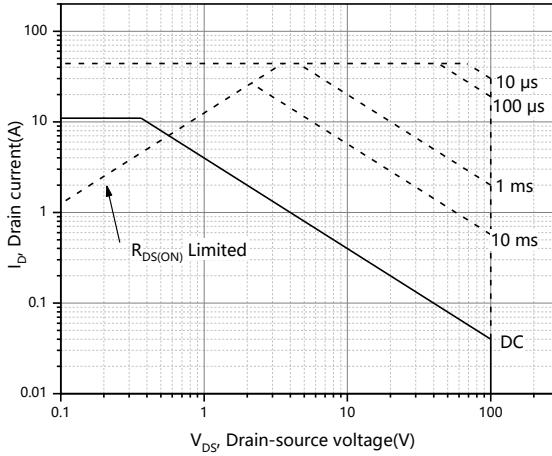
Figure 10. Safe operation area T$_C$=25 °C

Test circuits and waveforms

Figure 1. Gate charge test circuit & waveform
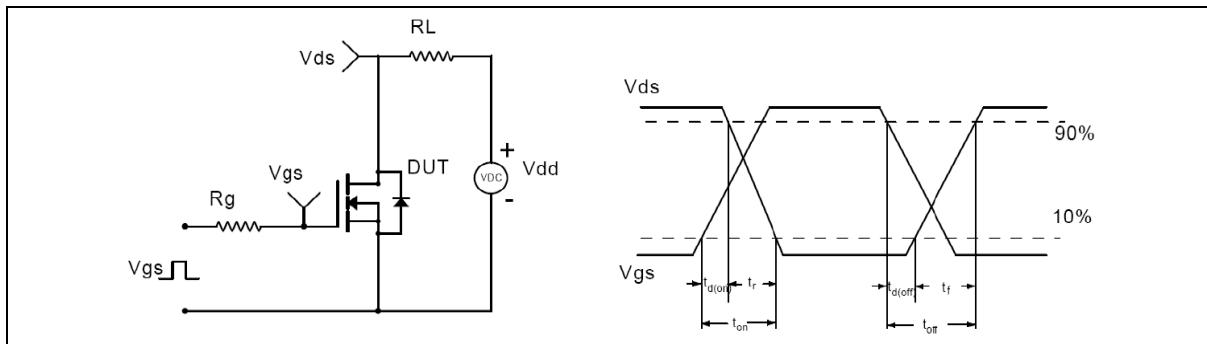
Figure 2. Switching time test circuit & waveforms
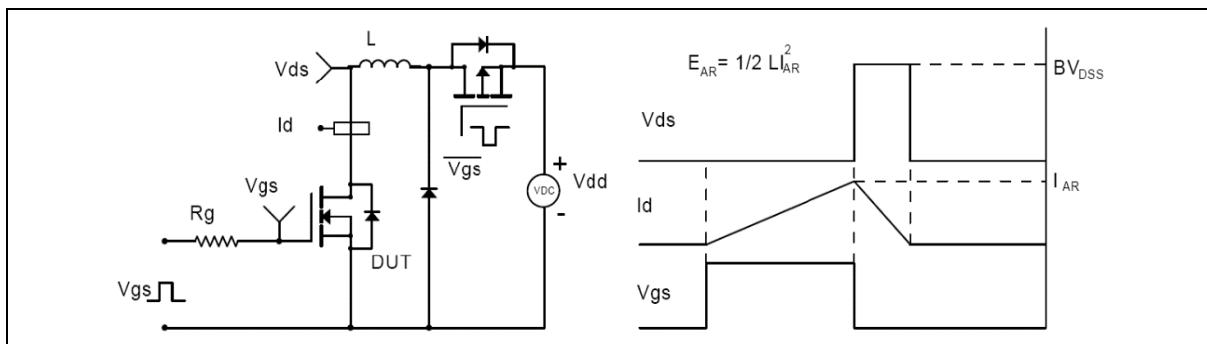
Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms
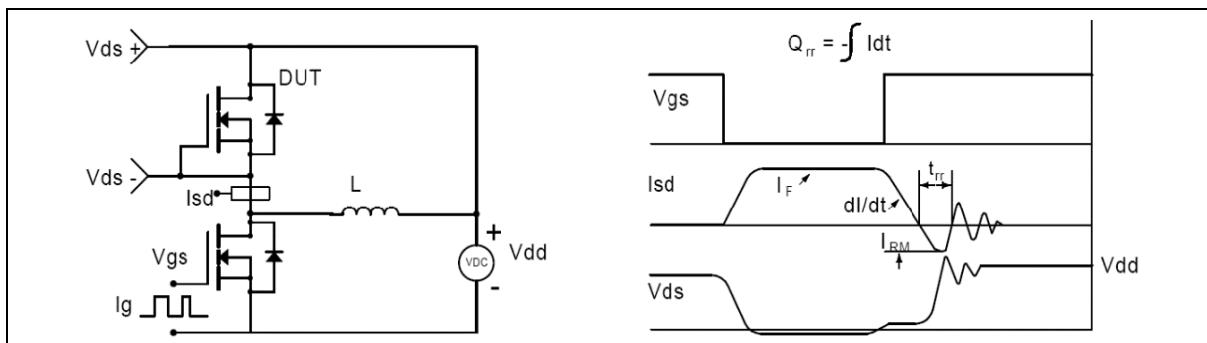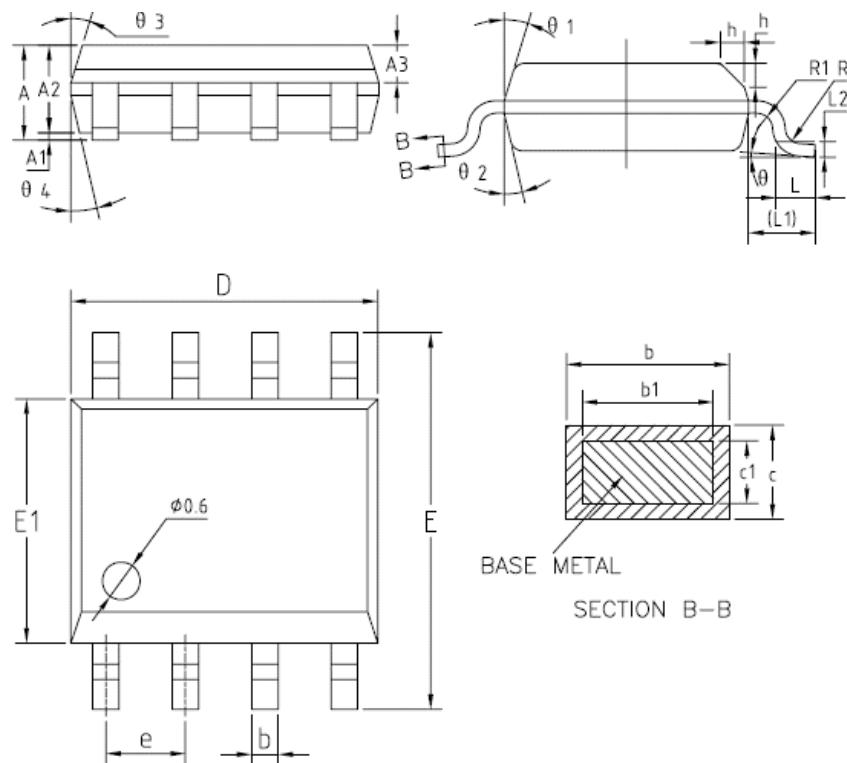
Figure 4. Diode reverse recovery test circuit & waveforms

Package Information

Symbol	mm		
	Min	Nom	Max
A	1.35	1.55	1.75
A1	0.10	0.15	0.25
A2	1.25	1.40	1.65
A3	0.50	0.60	0.70
b	0.38	-	0.51
L1	1.04REF		
L2	0.25BSC		
b1	0.37	0.42	0.47
c	0.18	-	0.25
c1	0.17	0.20	0.23
D	4.80	4.90	5
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.17	1.27	1.37
L	0.45	0.60	0.80
R	0.07	-	-
R1	0.07	-	-
h	0.30	0.40	0.50
θ	0°	-	8°
θ1	15°	17°	19°
θ2	11°	13°	15°
θ3	15°	17°	19°
θ4	11°	13°	15°

Version 1: SOP8-K package outline dimension

Ordering Information

Package Type	Units/ Reel	Reels/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
SOP8-K	2500	2	5000	6	30000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG08S10BF	SOP8	yes	yes	yes

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